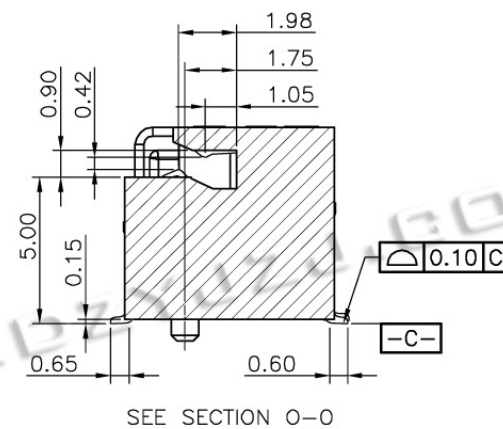
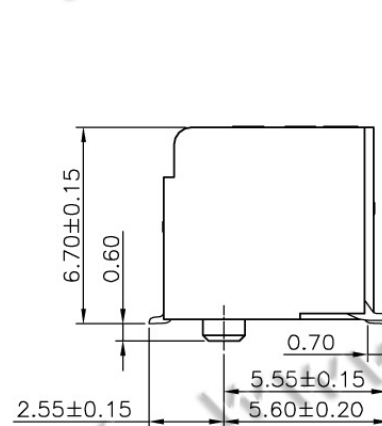
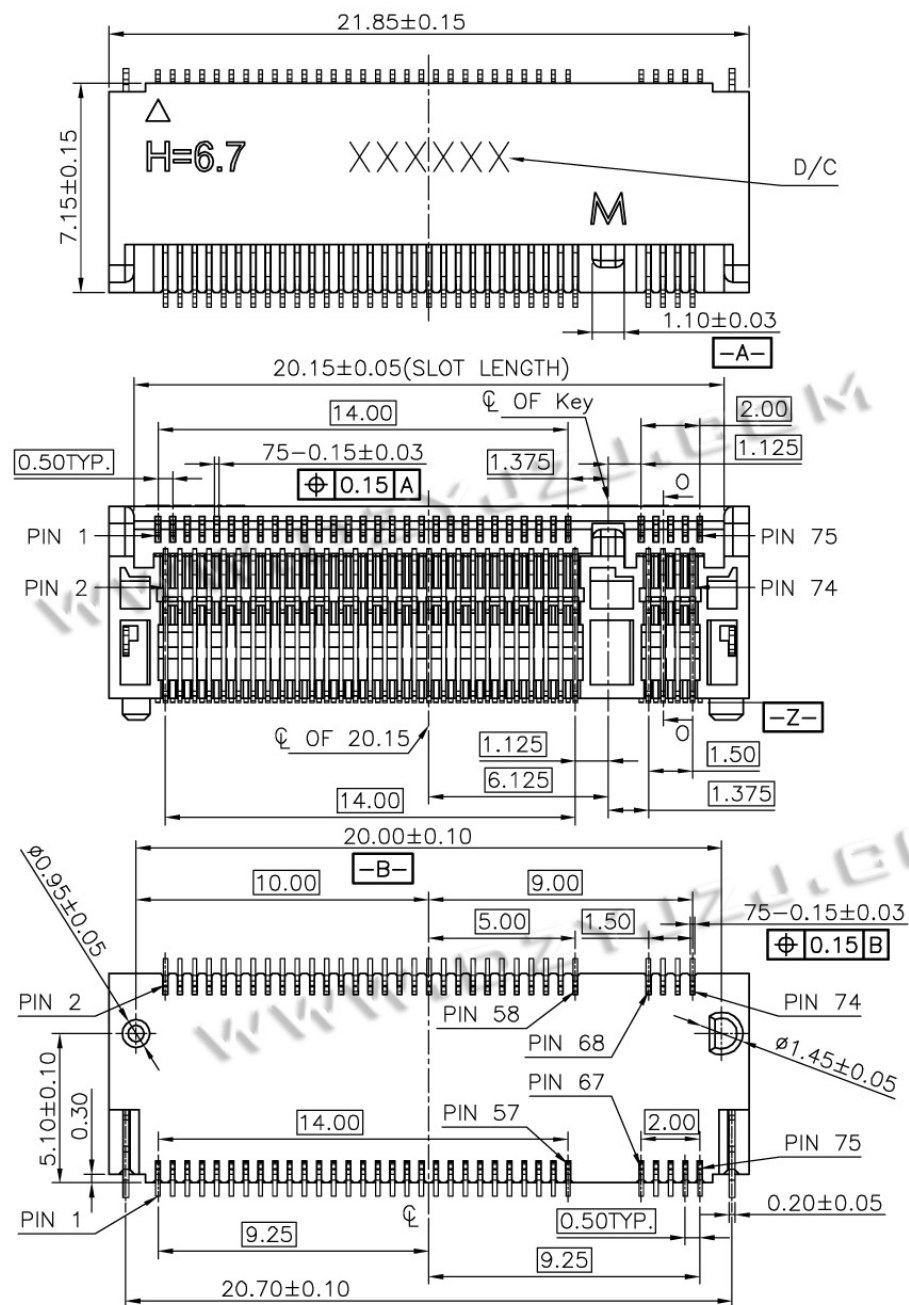
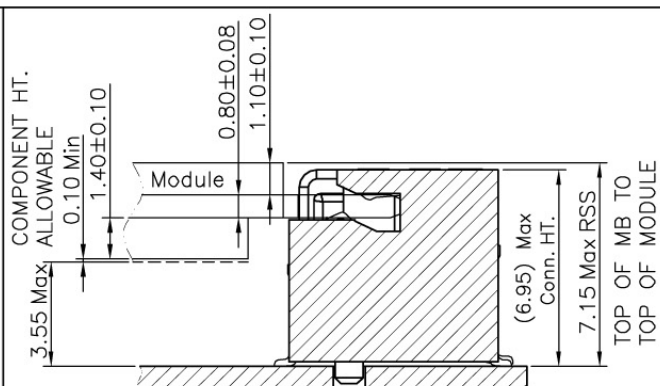


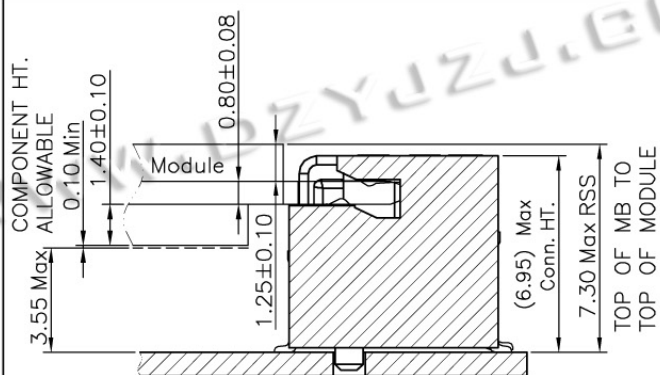


		深圳市华宇创精密电子有限公司	
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*		DRAWN BY : 陈一鸣	DATE : 2014-02-23
		PART NAME: 0.5MM PITCH M.2 H6.7 (KEY M)	
		CHECKED BY: 马跃	DATE : 2014-02-23
		PART NO.	HYC23M-05NGFF-670
		MOLD NO.	
		APPROVED BY: 柯南	DATE : 2014-02-23
UNIT: mm [inch]		DRAW NO:	HYC-1920011328
SCALE:1:1	SIZE: A4	SHEET NO.	1 OF 1

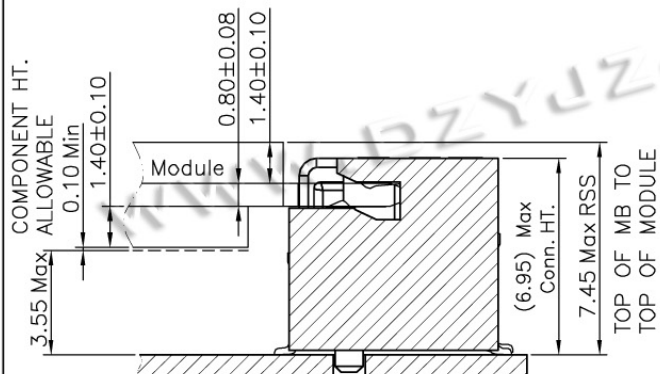
Assembly stack height schematic diagram



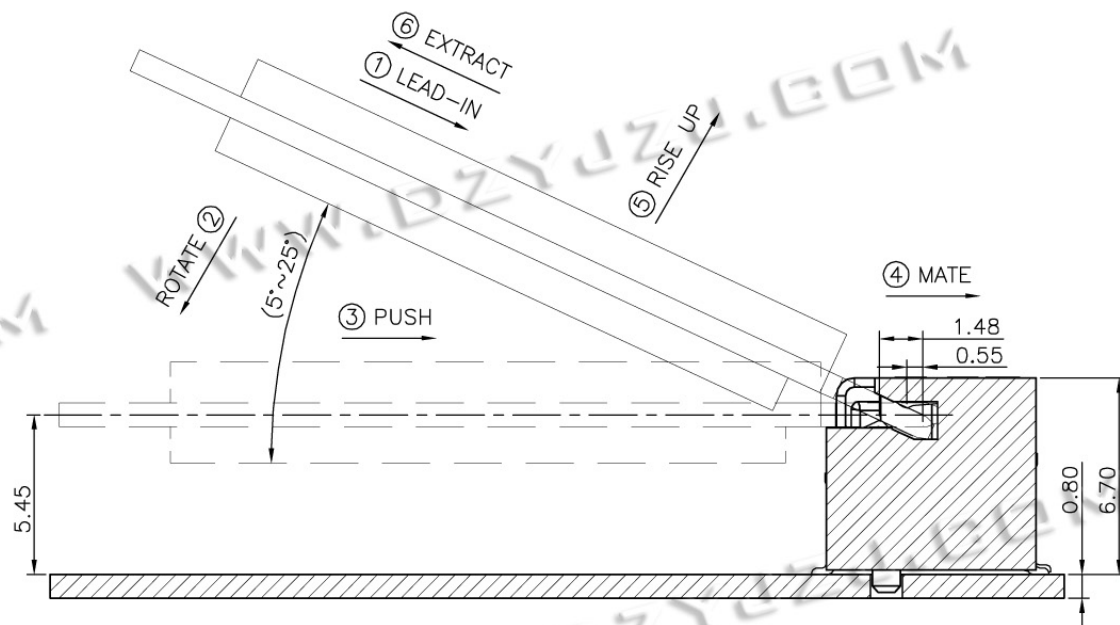
Stack-up Top Mount Double Sided Module for 1.20 max top-side component height



Stack-up Top Mount Double Sided Module for 1.35 max top-side component height



Stack-up Top Mount Double Sided Module for 1.50 max top-side component height



HOW TO MATE AND EXTRACT

MATE: ① → ④

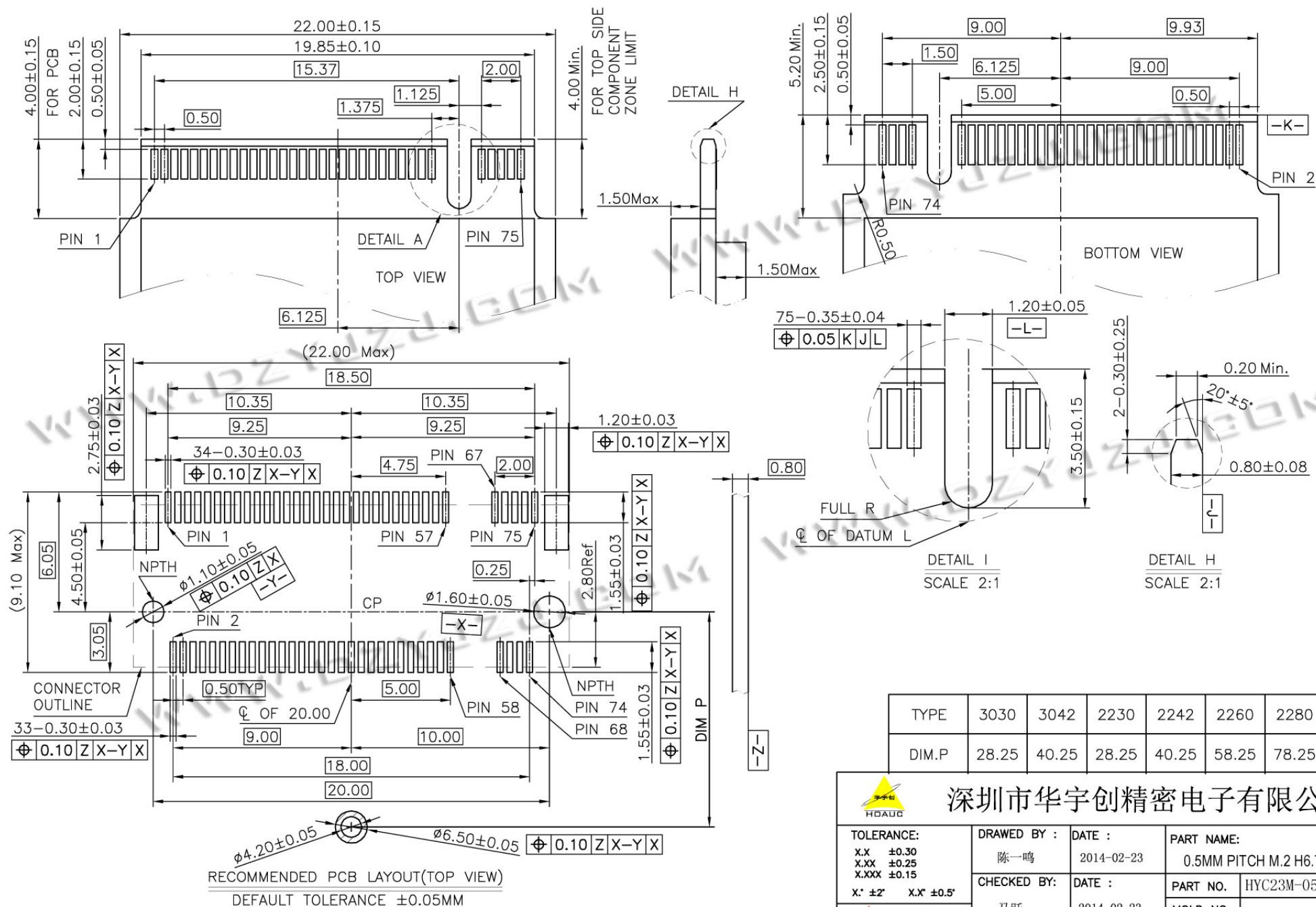
EXTRACT: ⑤ → ⑥

NOTE: Mating force will generate from step 3 to step 4.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2° X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.5MM PITCH M.2 H6.7 (KEY M)	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC23M-05NGFF-670
 UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 柯南	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-1920011328
			SHEET NO.	1 OF 1



TYPE	3030	3042	2230	2242	2260	2280	22110
DIM.P	28.25	40.25	28.25	40.25	58.25	78.25	108.25



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2° X.X° ±0.5°				0.5MM PITCH M.2 H6.7 (KEY M)	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC23M-05NGFF-670
		马跃	2014-02-23	MOLD NO.	
SCALE:1:1 SIZE: A4		APPROVED BY:	DATE :	DRAW NO:	HYC-1920011328
		柯南	2014-02-23	SHEET NO.	1 OF 1